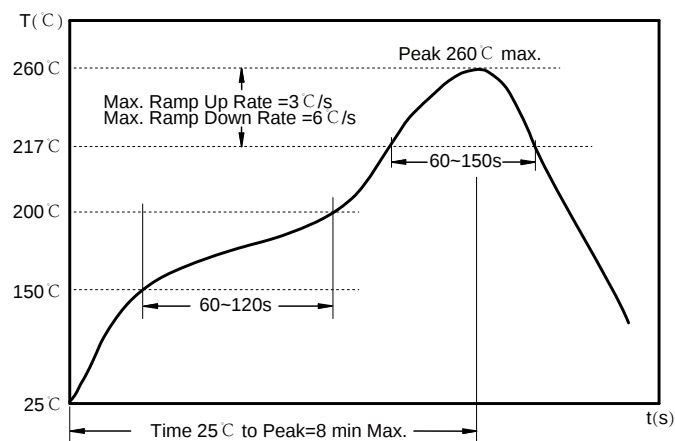


Soldering Reflow:



Preheat condition: $150 \sim 200^{\circ}\text{C}$ / 60~120 sec.
Allowed time above 217°C : 60~150 sec.
Max temperature: 260°C .

Allowed Reflow time: 2x max.

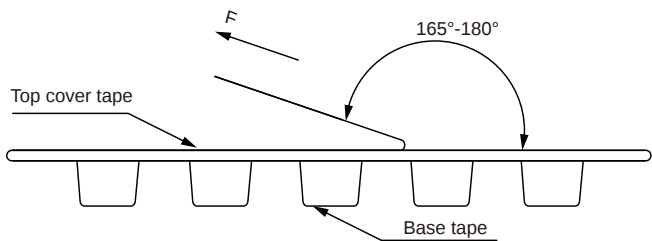
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA5030HT	5.75 ± 0.1	6.05 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	8.0 ± 0.1	12.0 ± 0.3	3.6 ± 0.1	1.75 ± 0.1	0.35 ± 0.05

Peel force of top cover tape:

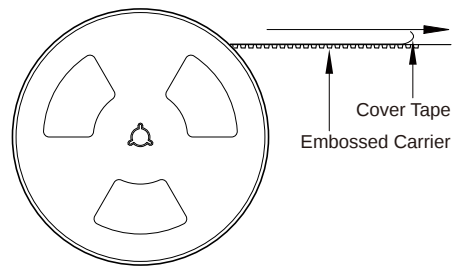


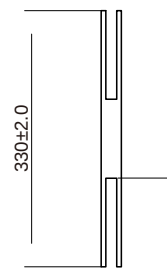
The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	K+Printing (Inductance+period)
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Reel Dimension: [mm]





Packaging Quantity: